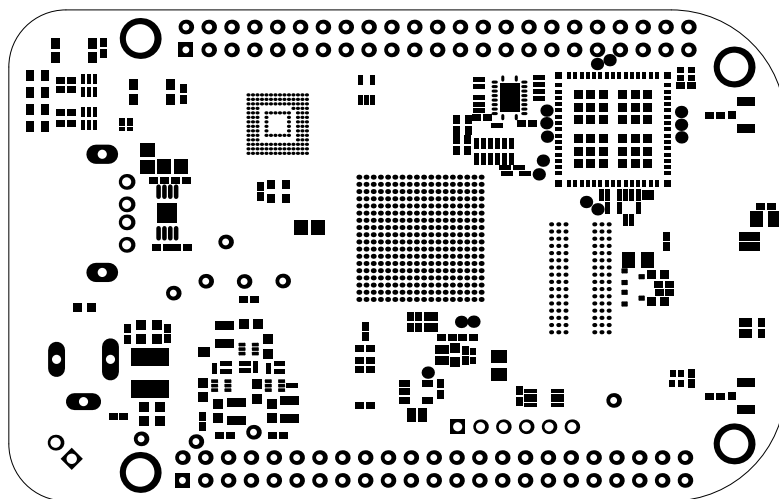
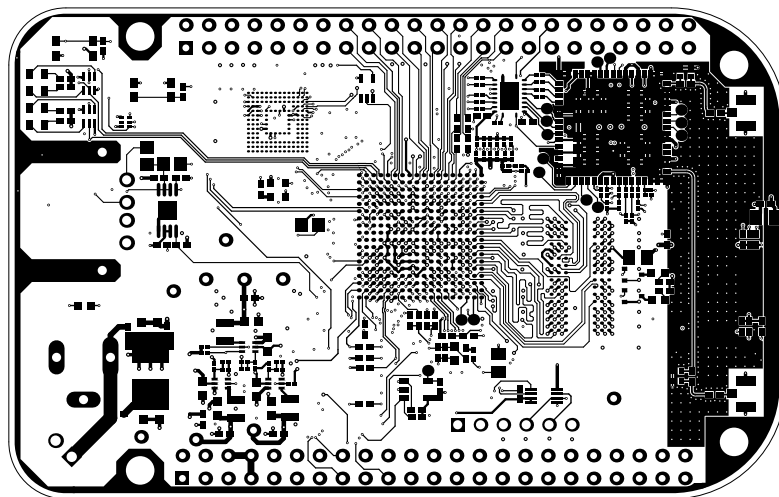


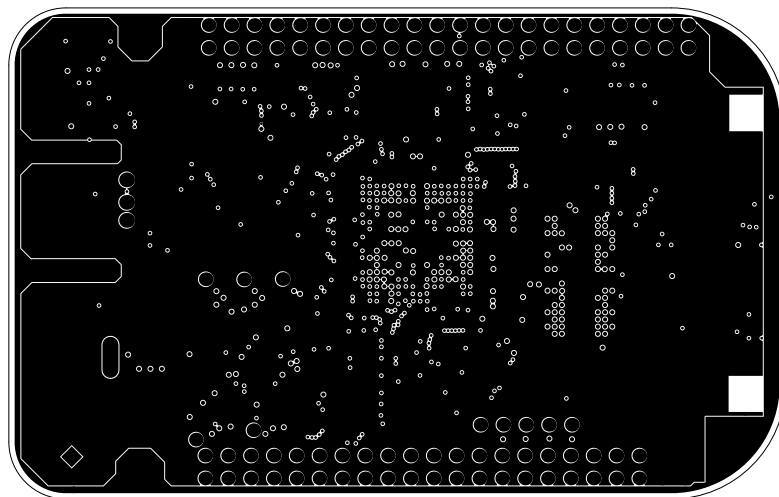
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01568		
PLOT NAME = Top Overlay	GENERATED : 4/11/2018	1:41:48 PM	TEXAS INSTRUMENTS



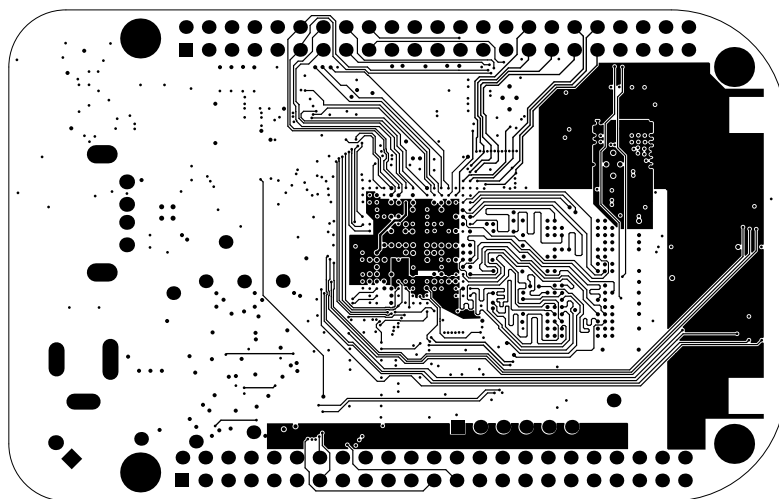
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01568		
PLOT NAME = Top Solder Mask	GENERATED : 4/11/2018 1:41:51 PM	TEXAS INSTRUMENTS	



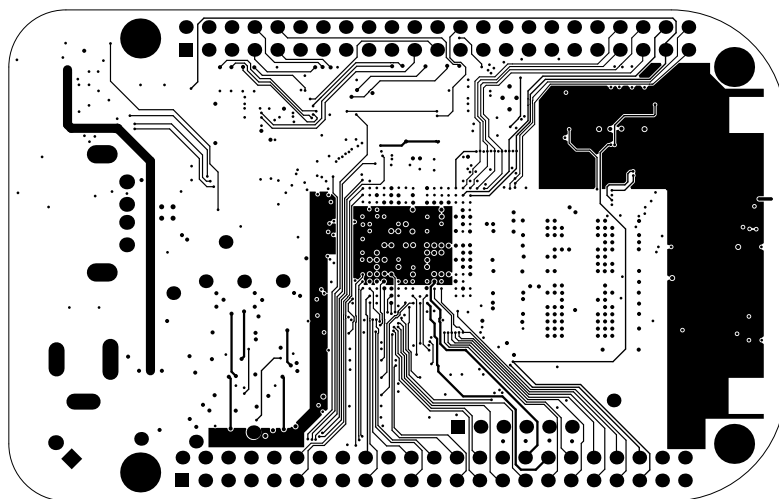
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01568		
PLOT NAME = Top Layer	GENERATED : 4/11/2018 1:41:54 PM	TEXAS INSTRUMENTS	



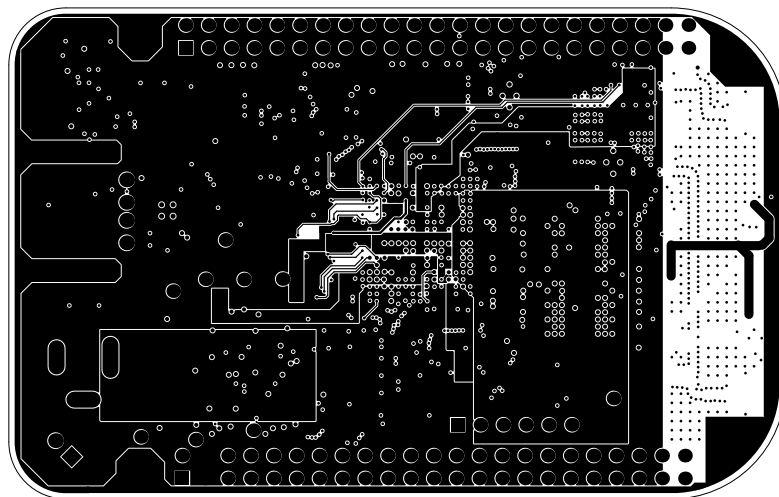
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01568		
PLOT NAME = Signal 1	GENERATED : 4/11/2018 1:41:56 PM	TEXAS INSTRUMENTS	



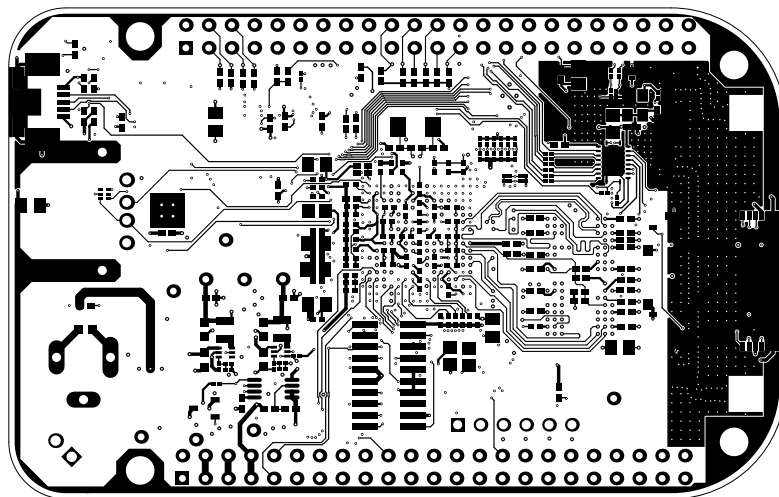
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01568		
PLOT NAME = Signal 2	GENERATED : 4/11/2018 1:41:59 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01568		
PLOT NAME = Signal 3	GENERATED : 4/11/2018 1:42:01 PM	TEXAS INSTRUMENTS	

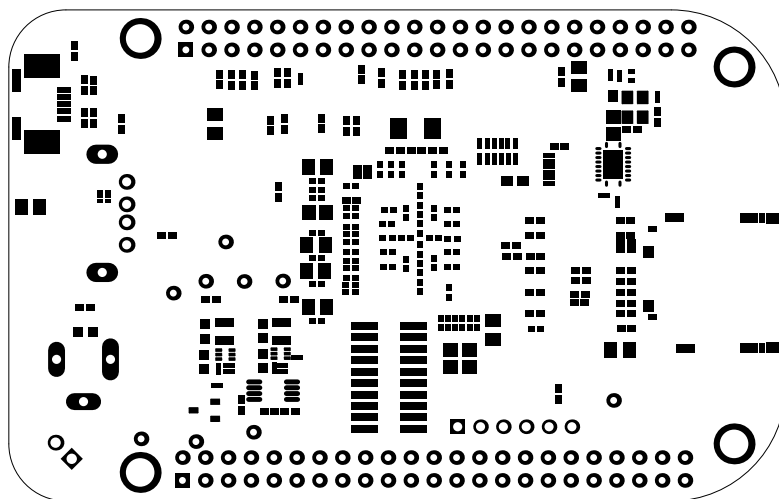


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01568		
PLOT NAME = Signal 4	GENERATED : 4/11/2018 1:42:04 PM	TEXAS INSTRUMENTS	

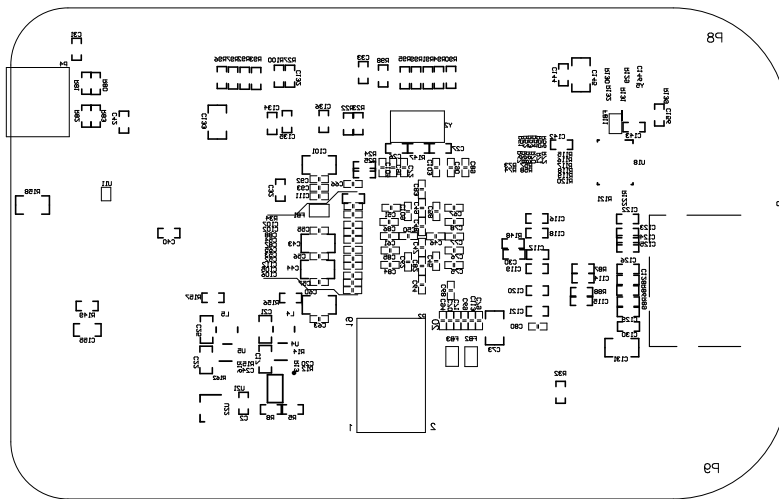


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01568		
PLOT NAME = Bottom Layer	GENERATED : 4/11/2018 1:42:06 PM	TEXAS INSTRUMENTS	

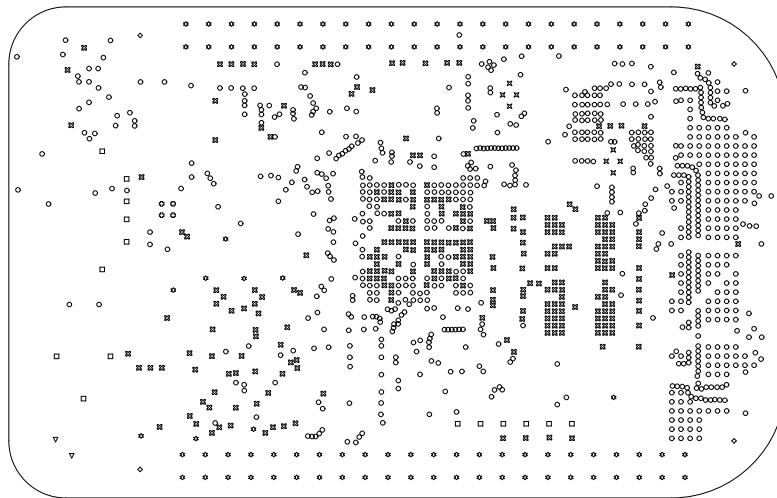




ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01568		
PLOT NAME = Bottom Solder Mask	GENERATED : 4/11/2018 1:42:09 PM	TEXAS INSTRUMENTS	

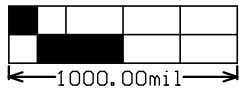


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01568		
PLOT NAME = Bottom Overlay	GENERATED : 4/11/2018 1:42:11 PM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	827	6.00mil (0.152mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	8	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	291	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	101	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
□	15	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
◇	4	125.00mil (3.175mm)	PTH	Round	Top Layer - Bottom Layer	
	1252 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01568		
PLOT NAME = Drill Drawing	GENERATED : 4/11/2018	1:42:14 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01568		
PLOT NAME = Board Dimensions	GENERATED : 4/11/2018 1:42:18 PM	TEXAS INSTRUMENTS	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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